

## P-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)			
-40	0.011 at V <sub>GS</sub> = -10 V	-48			
	0.016 at V <sub>GS</sub> = -4.5 V	-40			

#### **FEATURES**

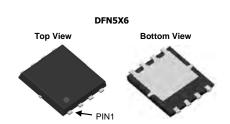
- DT-Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested

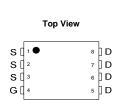
#### **APPLICATIONS**

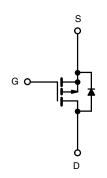
- Notebook
  - Load Switch



RoHS







P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	Limit	UNIT	
Drain-Source Voltage		$V_{DS}$	- 40	V	
Gate-Source Voltage		$V_{GS}$	± 20	V	
Continuos Dunio Comunit /T. 150 °C\ 3	T <sub>A</sub> = 25 °C	- 48			
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C	I <sub>D</sub>	- 35		
Pulsed Drain Current		I <sub>DM</sub>	- 190	Α	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	- 48		
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	- 35		
Single Pulse Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	113	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C	D	39	w	
iviaximum rower Dissipation "	T <sub>A</sub> = 70 °C	P <sub>D</sub>	25	VV	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Soldering Recommendations (Peak Temperature) b, c			260		

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient <sup>a</sup>	t ≤ 10 s	- R <sub>thJA</sub>	20	25	]	
Maximum Junction-to-Ambient ~	Steady State		25	35	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R <sub>thJC</sub>	2.1	3.3		

#### Notes

- a. Surface mounted on 1" x 1" FR4 board.
- b. TheDFN5x6isa leadlesspackage. The endof thelead terminalisexposed copper (not plated) as a result of the singulation process in manufacturing. A solderfillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.



PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static				_			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-1	-	-3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA	
Zava Cata Valtaga Dvain Couvent		$V_{DS} = -32 \text{ V}, V_{GS} = 0 \text{ V}$		-	-1	μА	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			-	-10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	-60	-	-	Α	
Dunin Course On State Projetones 3	В	$V_{GS} = -10 \text{ V}, I_D = -5 \text{ A}$	-	0.011	0.014	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5 V, I <sub>D</sub> = -3 A	-	0.016	0.022		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = -15 V, I <sub>D</sub> = -5 A	-	35	-	S	
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>S</sub> = -4.5 A, V <sub>GS</sub> = 0 V	-	-0.7	-1.2	V	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 V$	-	2120	-	pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 100 \text{ V},$	-	230	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz	-	180	-		
Total Gate Charge	Qg		-	121	-		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -20 \text{ V}, V_{GS} = -10 \text{ V}, I_D = -5 \text{ A}$	-	20	-	nC	
Gate-Drain Charge	Q <sub>gd</sub>		-	32	-		
Gate Resistance	$R_g$		-	1.5	-	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>		_	21	-		
Rise Time	t <sub>r</sub>	$V_{DD}$ = -20 V, $R_L$ = 30 $\Omega$	-	20	-		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong$ -5 A, $V_{GEN}=$ -10 V, $R_g=6~\Omega$	-	55	-	ns	
Fall Time	t <sub>f</sub>		-	12	-		
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = -4.5 A, dI/dt = 100 A/μs	-	29	50		

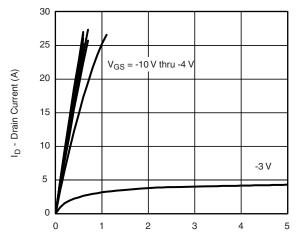
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

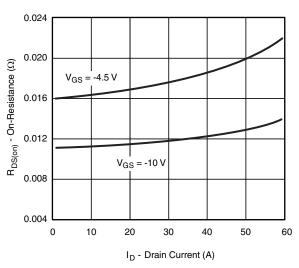


#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

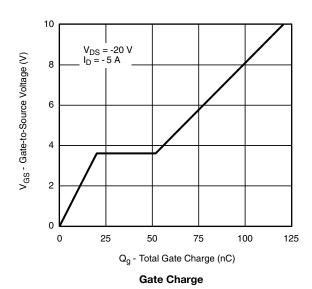


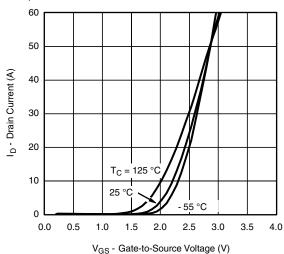
V<sub>DS</sub> - Drain-to-Source Voltage (V)

#### **Output Characteristics**

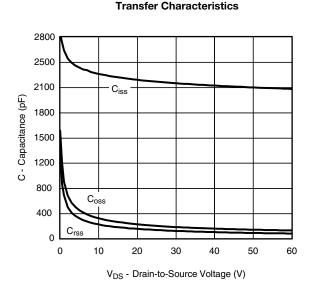


#### On-Resistance vs. Drain Current

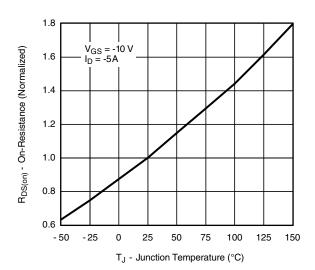




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Capacitance

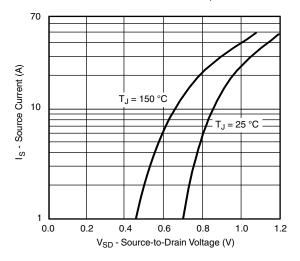


On-Resistance vs. Junction Temperature

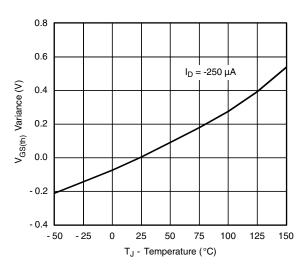




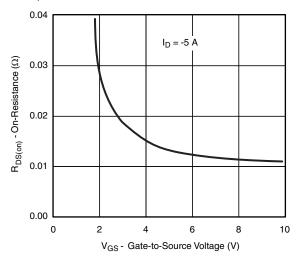
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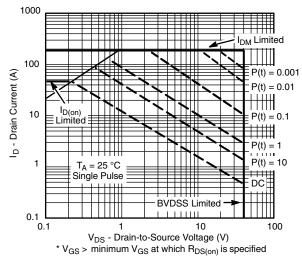
#### Source-Drain Diode Forward Voltage



**Threshold Voltage** 



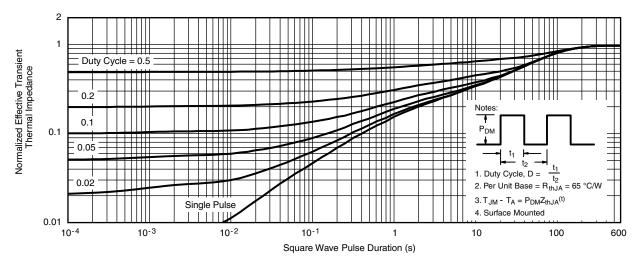
On-Resistance vs. Gate-to-Source Voltage



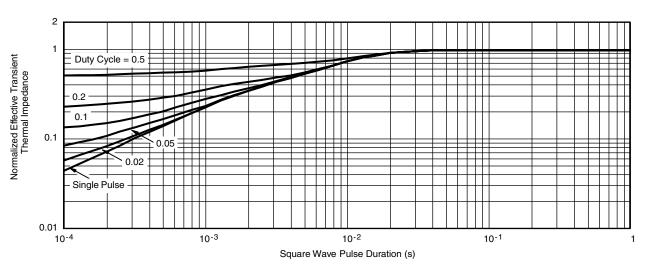
Safe Operating Area



#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

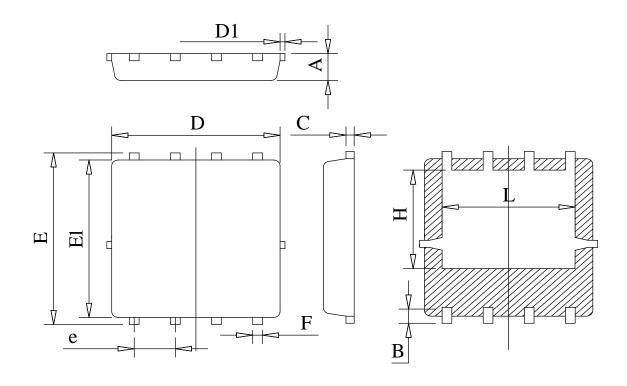


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

## DFN5X6-8L PACKAGE OUTLINE



# COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

Unit: mm

Symbol	Min	Тур	Max
A	0.78	0.95	1.12
В	0.45	0.58	0.78
С	0.18	0.254	0.36
D	4.70	5.20	5.45
D1			0.18
Е	5.85	6.05	6.25
E1	5.38	5.55	5.98
e	1.15	1.27	1.40
F	0.18	0.30	0.52
Н	3.25	3.47	3.70
L	3.75	4.00	4.25





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